

SKiiP 38NAB12T4V1

Features

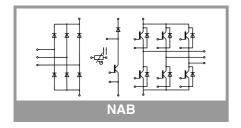
- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

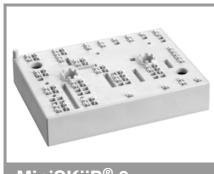
Typical Applications*

- Inverter up to 41 kVA
- Typical motor power 22 kW

- Max. case temperature limited to T_C=125°C
- Product reliability results valid for T_j≤150°C (recommended T_{j,op}=-40...+150°C)
- For short circuit: Soft R_{Goff} recommended
- MiniSKiiP "Technical Explanations" and "Mounting Instructions" are part of the data sheet. Please refer to both documents for further information.

Absolute	Maximum Ratings	5			
Symbol	Conditions		Values	Unit	
Inverter -	IGBT			•	
V _{CES}	T _j = 25 °C		1200	V	
Ic	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	115	Α	
T _j = 175 °C	T _s = 70 °C	93	Α		
Ic	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	140	Α	
	T _j = 175 °C	T _s = 70 °C	114	Α	
I _{Cnom}		•	100	Α	
I _{CRM}	I _{CRM} = 3 x I _{Cnom}		300	Α	
V _{GES}			-20 20	V	
	$V_{CC} = 800 \text{ V}$				
t _{psc}	V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 150 °C	10	μs	
Tj			-40 175	°C	
Chopper	- IGBT				
V _{CES}	T _j = 25 °C		1200	V	
Ic	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	115	Α	
	T _j = 175 °C	T _s = 70 °C	93	Α	
Ic	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	140	Α	
	T _j = 175 °C	T _s = 70 °C	114	Α	
I _{Cnom}			100	Α	
I _{CRM}	I _{CRM} = 3 x I _{Cnom}		300	Α	
V _{GES}			-20 20	V	
t _{psc}	$V_{CC} = 800 \text{ V}$ $V_{GE} \le 15 \text{ V}$ $V_{CES} \le 1200 \text{ V}$	T _j = 150 °C	10	μs	
T _i	V CES S 1200 V		-40 175	°C	
Inverse -	Diode		10 170		
V _{RRM}	T _i = 25 °C		1200	V	
I _F	$\lambda_{\text{paste}} = 0.8 \text{ W/(mK)}$	T _s = 25 °C	99	A	
'F	$T_i = 175 ^{\circ}\text{C}$	$T_s = 70 ^{\circ}\text{C}$	79	A	
I _F		T _s = 25 °C	116	A	
'F	λ_{paste} =2.5 W/(mK) T _i = 175 °C	T _s = 70 °C	93	A	
1_	1,1-1100	18-70 0	100	A	
I _{Fnom}	I _{FRM} = 3 x I _{Fnom}		300	A	
I _{FRM}	$t_p = 10 \text{ ms, sin } 180^\circ$. T. = 150 °C	550	A	
I _{FSM}	tp = 10 1113, 311 100	, 1, = 130 0			
	olion Diodo		-40 173	°C	
	eling - Diode		1000	1 1/	
V _{RRM}	T _j = 25 °C	T 05.00	1200	V	
I _F	$\lambda_{\text{paste}} = 0.8 \text{ W/(mK)}$	T _s = 25 °C	100	A	
	T _j = 175 °C	T _s = 70 °C	79	A	
	$\lambda_{\text{paste}} = 2.5 \text{ W/(mK)}$	T _s = 25 °C	116	A	
	T _j = 175 °C	T _s = 70 °C	93	A	
I _{Fnom}			100	Α	
I _{FRM}	$I_{FRM} = 3 \times I_{Fnom}$		300	Α	
I _{FSM}	$t_p = 10 \text{ ms, sin } 180^{\circ}, T_j = 150 {}^{\circ}\text{C}$		550	Α	
Tj			-40 175	°C	





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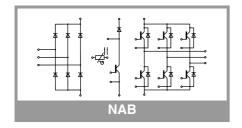
Typical Applications*

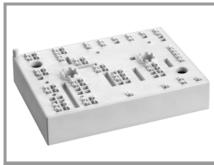
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Absolute	Maximum Ratings	S		
Symbol	Conditions		Values	Unit
Rectifier -	- Diode			·
V_{RRM}	T _j = 25 °C		1600	V
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	117	Α
	T _j = 150 °C	T _s = 70 °C	86	Α
I _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	136	Α
	T _j = 150 °C	T _s = 70 °C	101	Α
I _{Fnom}			45	Α
I _{FSM}	10 ms sin 180°	T _j = 25 °C	1000	Α
		T _j = 150 °C	890	Α
l ² t	10 ms sin 180°	T _j = 25 °C	5000	A ² s
		T _j = 150 °C	3900	A ² s
Tj			-40 150	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C, 20 A per spring		80	Α
T _{stg}			-40 125	°C
V _{isol}	AC sinus 50 Hz, 1 min		2500	V

Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
Inverter - IGBT								
V _{CE(sat)}	$V_{CE(sat)}$ $V_{CE} = 100 \text{ A}$ $V_{GE} = 15 \text{ V}$ chiplevel	T _j = 25 °C		1.80	2.05	V		
		T _j = 150 °C		2.20	2.40	V		
V _{CE0}	chiplevel	T _j = 25 °C		0.80	0.90	V		
	Chipievei	T _j = 150 °C		0.70	0.80	V		
r _{CE}	$V_{GE} = 15 \text{ V}$	$T_j = 25 ^{\circ}C$		10	12	mΩ		
chiplevel	T _j = 150 °C		15	16	$m\Omega$			
$V_{GE(th)}$	$V_{GE} = V_{CE} V$, $I_C = 4 \text{ mA}$		5	5.8	6.5	V		
I _{CES}	$V_{GE} = 0 \text{ V}, V_{CE} = 1$	200 V, T _j = 25 °C		0.1	0.3	mA		
C _{ies}	V 05.V	f = 1 MHz		6.15		nF		
Coes	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		0.41		nF		
C _{res}		f = 1 MHz		0.35		nF		
Q_G	- 8 V+ 15 V			565		nC		
R _{Gint}	T _j = 25 °C			7.5		Ω		
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C		160		ns		
t _r	I _C = 100 A	T _j = 150 °C		35		ns		
E _{on}	$R_{G \text{ on}} = 1 \Omega$ $R_{G \text{ off}} = 1 \Omega$	T _j = 150 °C		11.2		mJ		
t _{d(off)}		T _j = 150 °C		390		ns		
t _f		T _j = 150 °C		75		ns		
E _{off}	V _{GE} = +15/-15 V	T _j = 150 °C		10		mJ		
R _{th(j-s)}	per IGBT, λ _{paste} =0.8 W/(mK)			0.48		K/W		
R _{th(j-s)}	per IGBT, λ _{paste} =2.5 W/(mK)			0.34		K/W		





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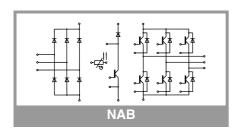
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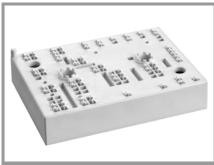
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Characte	eristics					
Symbol	Conditions		min.	typ.	max.	Unit
Chopper	- IGBT					
V _{CE(sat)}	I _C = 100 A	T _j = 25 °C		1.80	2.05	V
	V _{GE} = 15 V chiplevel	T _j = 150 °C		2.20	2.40	V
V _{CE0}	abialoval	T _j = 25 °C		0.80	0.90	V
	chiplevel	T _j = 150 °C		0.70	0.80	V
r _{CE}	$V_{GE} = 15 \text{ V}$	T _j = 25 °C		10	12	mΩ
	chiplevel	T _j = 150 °C		15	16	mΩ
$V_{\text{GE(th)}}$	$V_{GE} = V_{CE} V, I_C = 4$		5	5.8	6.5	V
I _{CES}	$V_{GE} = 0 \text{ V}, V_{CE} = 12$	00 V, T _j = 25 °C		0.1	0.3	mA
Q_G	- 8 V+ 15 V			565		nC
R _{Gint}	T _j = 25 °C			7.5		Ω
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C		160		ns
t _r	$I_C = 100 \text{ A}$ $R_{G \text{ on}} = 1 \Omega$	T _j = 150 °C		35		ns
E _{on}	$R_{G \text{ off}} = 1 \Omega$	T _j = 150 °C		11.2		mJ
t _{d(off)}		T _j = 150 °C		390		ns
t _f		T _j = 150 °C		75		ns
E _{off}	V _{GE} = +15/-15 V	T _j = 150 °C		10		mJ
R _{th(j-s)}	per IGBT, λ _{paste} =0.8	W/(mK)		0.48		K/W
R _{th(j-s)}	per IGBT, λ _{paste} =2.5	5 W/(mK)		0.34		K/W
Inverse -	Diode					
$V_F = V_{EC}$	I _F = 100 A	T _j = 25 °C		2.20	2.52	V
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.15	2.47	V
V_{F0}	chiployel	T _j = 25 °C		1.30	1.50	V
	chiplevel	T _j = 150 °C		0.90	1.10	V
r _F	chiplevel	T _j = 25 °C		9.0	10	mΩ
	Chipievei	T _j = 150 °C		13	14	mΩ
I _{RRM}	I _F = 100 A	T _j = 150 °C		82		Α
Q _{rr}	di/dt _{off} = 2400 A/μs V _{GE} = -15 V	T _j = 150 °C		16.4		μC
E _{rr}	$V_{GE} = -15 \text{ V}$ $V_{CC} = 600 \text{ V}$	T _j = 150 °C		6.5		mJ
R _{th(j-s)}	per Diode, $\lambda_{paste}=0$.	8 W/(mK)		0.66		K/W
R _{th(j-s)}	per Diode, λ_{paste} =2.			0.52		K/W
	eling - Diode					1
$V_F = V_{EC}$	I _F = 100 A	T _j = 25 °C		2.20	2.52	V
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.15	2.47	V
V _{F0}		T _i = 25 °C		1.30	1.50	V
-	chiplevel	T _j = 150 °C		0.90	1.10	V
r _F		T _j = 25 °C		9.0	10	mΩ
	chiplevel	T _j = 150 °C		13	14	mΩ
I _{RRM}	I _F = 100 A	T _j = 150 °C		82		Α
Q _{rr}	$di/dt_{off} = 2400 \text{ A/}\mu\text{s}$	T _j = 150 °C		16.4		μC
E _{rr}	$V_{GE} = -15 \text{ V}$ $V_{CC} = 600 \text{ V}$	T _i = 150 °C		6.5		mJ
R _{th(j-s)}	per Diode, $\lambda_{paste}=0$.	*		0.66		K/W
R _{th(j-s)}	per Diode, λ_{paste} =2.			0.52		K/W
-u i(j-3)	po. 5.635, //paste=2.6 **/(1114)					





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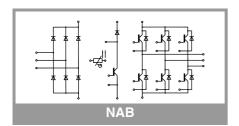
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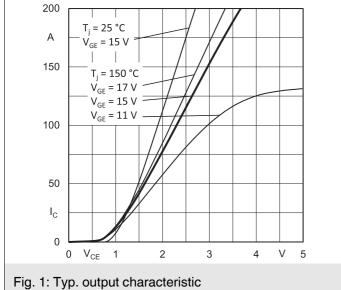
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Rectifier -	- Diode					
$V_F = V_{EC}$	$I_{F} = 45 \text{ A}$	T _j = 25 °C		1.00	1.21	V
	V _{GE} = 0 V chiplevel	T _j = 125 °C		0.90	1.10	V
V_{F0}	/ _{F0} chiplevel	T _j = 25 °C		0.88	0.98	V
	Criipievei	T _j = 125 °C		0.73	0.83	V
r _F	chiplevel	T _j = 25 °C		2.7	5.1	mΩ
	Chipievei	T _j = 125 °C		3.8	6.0	mΩ
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(mK)			0.7		K/W
R _{th(j-s)}	per Diode, λ _{paste} =2.5 W/(mK)			0.56		K/W
Module						
Ms	to heat sink		2		2.5	Nm
w				82		g
L _{CE}						nH
Temperat	ture Sensor					
R ₁₀₀	T _r = 100 °C, tolerance = 3 %			1670 ± 3%		Ω
R(T)	R(T)=1000 Ω [1+A(T-25°C)+B(T-25°C) ²], A = 7.635*10 ⁻³ °C ⁻¹ , B = 1.731*10 ⁻⁵ °C ⁻²					





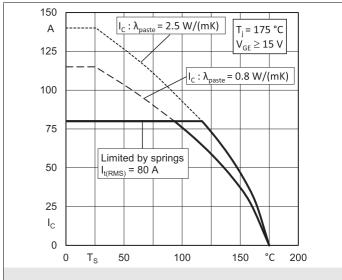


Fig. 2: Typ. rated current vs. temperature $I_C = f(T_S)$

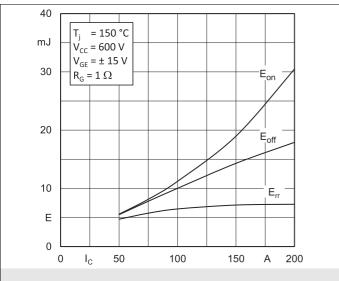


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

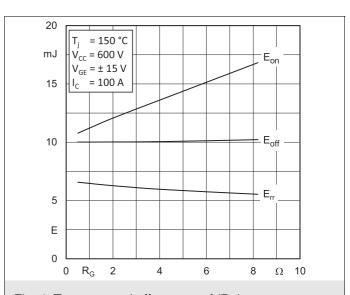


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

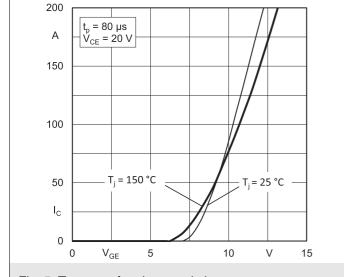


Fig. 5: Typ. transfer characteristic

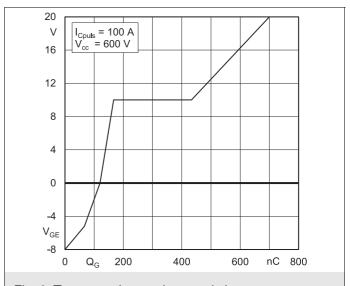
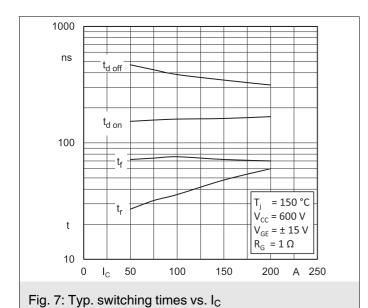
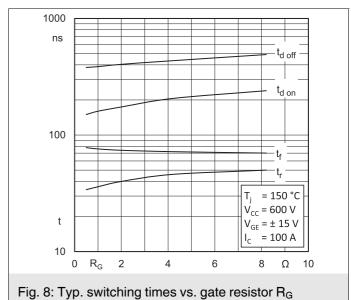
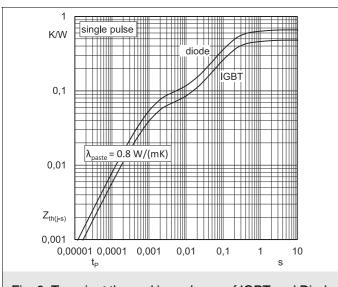
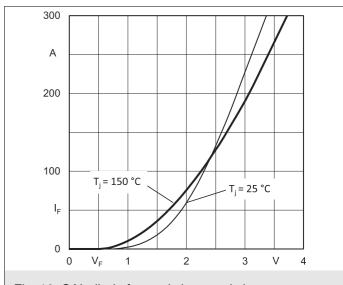


Fig. 6: Typ. gate charge characteristic

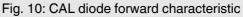


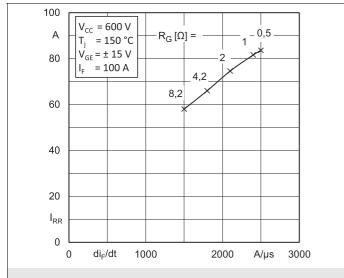


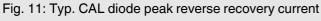












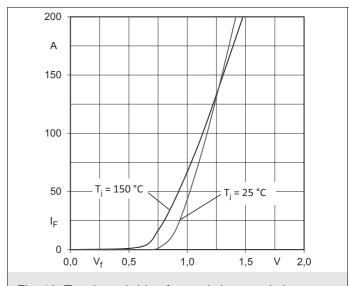
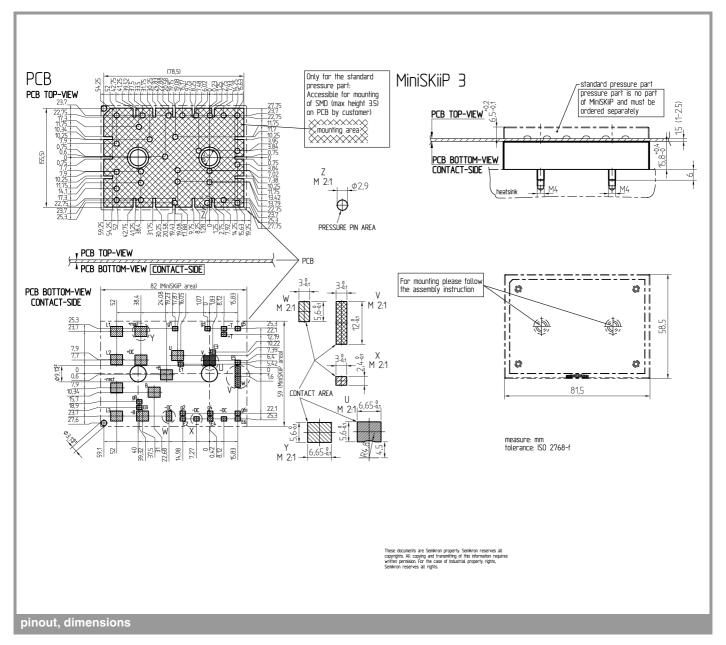
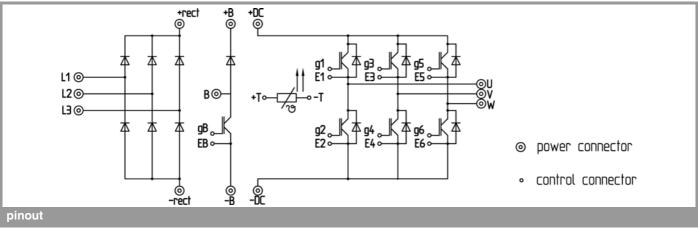


Fig. 12: Typ. input bridge forward characteristic





This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

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